26th annual IEEE Wireless and Microwave Technology Conference
Cocoa Beach, Florida, on April 14-15, 2025

Student Day

Date: Apr 15th, 2025

Time: 10 AM – 5 PM

Location: Hilton Cocoa Beach, 1550 North Atlantic Ave, Cocoa Beach, Florida, 32931

WAMICON is deploying the **"Student Day"** program for 2025 to offer the opportunity to undergraduate and graduate students from Florida's top electrical engineering programs to participate in a day at the conference filled with technical presentations, design competitions, networking sessions, and more.

Event Description:

- 'Ask-Us-anything' - students will be guided through a fun & interactive panel session where students can ask professional growth/career guidance questions
- 'Cadence workshop' – on Multi-fabric, heterogeneous integration of RF systems (details on pg-2)
- 'Exhibitor Showcase' – Engage with industry professionals through live demonstrations, prototypes, and technical discussions, fostering networking and collaboration
- And much more

Benefits for the Students:

- Full-day at the conference with complete access to all presentations and exhibits,
- Experience cutting-edge RF and microwave components, test equipment, and simulation tools
- Offset Transportation cost from and to their university.
- Young Professionals and Women in Microwave panel, with career advice from leaders in the discipline.
- Networking opportunities and a tour of the exhibition area.
- Meals and receptions.

To register, click here or scan the QR code.

For questions regarding student activities, contact: Satheesh Bojja, sbojjave@fiu.edu

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Cadence Workshop

Combining different types of semiconductors into a single system allows size and power reduction while providing higher performance RF, photonics, and wired interfaces. Integrating chiplets allows circuits to be implemented with individual but optimal processes, leading to overall reduced cost and faster time to market. The Cadence Virtuoso Heterogeneous Integration (HI) workflow allows designers to meet heterogeneous design challenges, such as multi-fabric co-analysis of electrical, electromagnetic (EM), RF and photonic signals, as well as system-level integration and verification, including power and thermal analysis. This workshop presents the latest advances in multi-fabric design, analysis and manufacturing verification with a particular focus on working with RF IP including III-V and Si MMICs, RFICs and laminates.

Moving from chips to chiplets using Virtuoso Heterogenous Integration flow:

- Assembly of multiple dies, packages and interposers in a single cockpit
- Package DRC and System LVS
- Die and System level Electromagnetic Analysis

Introducing Virtuoso Studio RF for Si MMIC design and analysis:

- Introduction to new platform for RF analysis of Virtuoso IP
- RF device/circuit characterization with measurement-based simulations
- Design Si MMIC IP with a RF/mw physical design workflow and Virtuoso PDKs
- Co-design off-chip RF laminate with embedded Virtuoso IP